Application Performance Plots

Orange Line (Channel 1) = Power Up Ramp on BAT Pin
Turquoise Line (Channel 2) = DOUT Gate Drive Output
DOUT goes from low to high when UVP Recovery = UVP Set Threshold +100 mV

Figure 27. UVP Recovery

Orange Line (Channel 1) = Power Down Ramp on BAT Pin
Turquoise Line (Channel 2) = DOUT Gate Drive Output
DOUT goes from high to low when UVP Set Threshold + set delay time

Figure 28. UVP Set Condition

Orange Line (Channel 1) = Power Up Ramp on BAT Pin
Turquoise Line (Channel 2) = COUT Gate Drive Output

Figure 29. Initial Power Up, DOUT

Orange Line (Channel 1) = Power Up Ramp on BAT Pin
Turquoise Line (Channel 2) = COUT Gate Drive Output
COUT goes from high to low when OVP threshold = OVP set Threshold + set delay time

Figure 30. Initial Power Up, COUT

Orange Line (Channel 1) = Decrease Voltage on BAT Pin
Turquoise Line (Channel 2) = COUT Gate Drive Output
COUT goes from low to high when OVP Recovery = OVP Set Threshold –100 mV

Figure 31. OVP Set Condition

Orange Line (Channel 1) = Decrease Voltage on BAT Pin
Turquoise Line (Channel 2) = COUT Gate Drive Output

Figure 32. OVP Recovery Condition
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